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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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preci-dip

PGA / BGA / PLCC SOCKETS

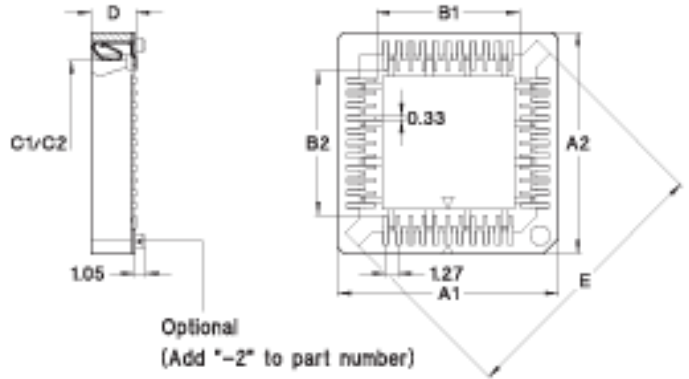
SERIES
540

540-88-XXX-17-400

PLCC

Socket for Plastic Leaded Chip carrier (PLCC), Surface mount

PLCC sockets with SMT terminations come with square sizes for IC-packages according to JEDEC MO-047, rectangular size (32) according to JEDEC MO-052 = low profile.



TECHNICAL SPECS.:

Insulator	Glass filled thermoplastic PPS-GF30-FR
Flammability	UL 94V-O
Contact	Phosphor bronze
Contact pressure	Min. 1.5 N per contact
Mechanical life	Min. 50 cycles
Rated current	1 A
Contact resistance	Max. 20 m
Dielectric strength	Min. 600 V RMS
Insulation resistance	Min. 5000 M
Capacitance	Max. 2 pF
Coplanarity SMD terminations	Max. 0.1 mm

ORDERING INFORMATION:

PP Plating code	Terminaison	Contact
88	Tin	Tin

Options: Tape & Reel packaging: add suffix -TR to part number. Parts with positioning pegs: add suffix -2 to part number (only available for No. of poles 32 and 68).

ADVANCED INFORMATION:

Order Codes	No of poles	A1/A2	B1/B2	C1/C2	D	E
540-88-020-17-400	20	14.86	7.02	9.20	4.60	16.00
540-88-028-17-400	28	17.34	9.50	11.76	4.60	19.70
540-88-032-17-400	32	16.95	9.40	11.60	3.80	22.00
540-88-044-17-400	44	22.42	14.50	16.70	4.60	27.00
540-88-052-17-400	52	25.40	17.24	19.46	4.60	30.80
540-88-068-17-400	68	30.54	22.26	24.40	4.60	37.65
540-88-084-17-400	84	35.56	27.34	29.58	4.60	45.10

TECHNICAL ASSISTANCE

GENERAL SPECIFICATIONS:

The values listed below are general specs applying for PRECI-DIP PGA, BGA and PLCC sockets. Please see individual catalog page for additional and product specific technical data.

Operating temperature range	-55 ... +125 °C
Climatic category (IEC)	55/125/21
Operating humidity range	annual mean 75 %
Max working voltage	100 VRMS/150 VDC (2.54 mm grid)

PRECI-DIP sockets are recognized by Underwriters Laboratories Inc. and listed under "Connectors for Use in Data, Signal, Control and Power Applications", File Nr. E174442

MECHANICAL CHARACTERISTICS:

Clip retention	Min. 40 N (no displacement under axial force applied)
Contact (sleeve / clip) retention	Min. 3.3 N acc. to MIL-DTL-83734, pt 4.6.4.2

ELECTRICAL CHARACTERISTICS:

Insulation resistance between any two adjacent contacts	Min. 10'000 M at 500 V AC
Capacitance between any two adjacent contacts	Max. 1 pF (PLCC max. 2 pF)
Self inductance per contact	Max. 2 nH

ENVIRONMENTAL CHARACTERISTICS:

The sockets withstand the following environmental tests without mechanical and electrical defects:

- Dry heat steady state IEC 60512-11-9.11i / 60068-2-2.Bb: 125 °C, 16h
- Damp heat cyclic IEC 60512-11-12.11m / 60068-2-30.Db: 25/55 °C, 90 – 100 %rH, 1 cycle of 24 h
- Cold steady state IEC 60512-11-10.11j / 60068-2-1.A: -55 °C, 2 h
- Thermal shock IEC 60512-11-4.11d / 60068-2-14.Na: -55/125 °C, 5 cycles 30 min
- Sinusoidal vibrations IEC 60512-6-4.6d / 60068-2-6.Fc: 10 to 500 Hz, 10 g, 1 octave/min, 10 cycles for each axis
- Shock IEC 60512-6-3.6c / 60068-2-27.Ea: 50 g, 11 ms, 3 shocks in three axis

During the above two tests no contact interruption >50 ns does appear.

- Solderability J-STD-002A, Test A, 245°C, 5 s solder alloy SnAg3.8Cu0.7
- Resistance to soldering heat J-STD-0020C, 260°C, 20 s
- Moisture sensitivity J-STD-020C level 1
- Resistance to corrosion :
 - 1) Salt spray test IEC 60068-2-11.Ka: 48 h
 - 2) Sulfur dioxide (SO₂) test IEC 60068-2-42 Kc: 96 h at 25 ppm SO₂, 25 °C, 75 %rH
 - 3) Hydrogen sulfide (H₂S) test IEC 60068-2-43 Kd: 96 h at 12 ppm H₂S, 25 °C, 75 %rH

SOLDERLESS COMPLIANT PRESS-FIT CHARACTERISTICS:

PRESS-FIT CHARACTERISTICS MEASURED ACC. TO IEC 60352-5

- Press-in force: 90 N max. (at min. hole dia.) / 65 N typ.
- Push-out force: 30 N min. (at max. hole dia.) / 50 N typ.
- Push-out 3rd cycle: 20 N min. (at max. hole dia.)

PCB HOLE DIMENSIONS

- 2.54 mm grid: Finished hole Ø: 1 + 0.09/-0.06 mm | Drilled hole Ø: 1.15 ± 0.02 mm

- Interstitial grid: Finished hole \varnothing : $0.7 + 0.09/-0.06$ mm | Drilled hole \varnothing : 0.8 ± 0.02 mm

PCB HOLE PLATING

- PCB surface finish: Hole plating
- Tin: 5-15 μm tin over min. 25 μm copper
- Copper: min. 25 μm copper
- Gold over nickel: 0.05-0.2 μm gold over 2.5-5 μm nickel over min. 25 μm copper